

**IN THE SPECIFICATION:**

Kindly replace the specification with the substitute specification that is submitted herewith (a red-lined version also is submitted for the Examiner's convenience).

**IN THE CLAIMS:**

Please cancel claims 2, 3, 8, 9 and 14 without prejudice and disclaimer.

Kindly amend pending claims 1, 4-7 and 10-13 to read as follows:

A<sup>2</sup>  
1. (Amended) A printed wiring board with an electronic component mounted on a circuit board in which the electronic component is provided with a heat radiating plate for conducting heat internally generated, comprising:

a first heat radiating pattern for conducting heat which is formed on a front surface of said electronic component, and connected to said heat radiating plate of the electronic component by soldering;

a second heat radiating pattern for conducting heat which is formed on a rear surface of said circuit board at a position being opposed to said electronic component, and

heat radiating means mounted on said second heat radiating pattern by soldering at a position being opposed to the electronic component, wherein

said heat radiating plate and said first radiating pattern have a same area whereas said second heat radiating pattern has a larger area than that of said first radiating pattern or said heat radiating plate.